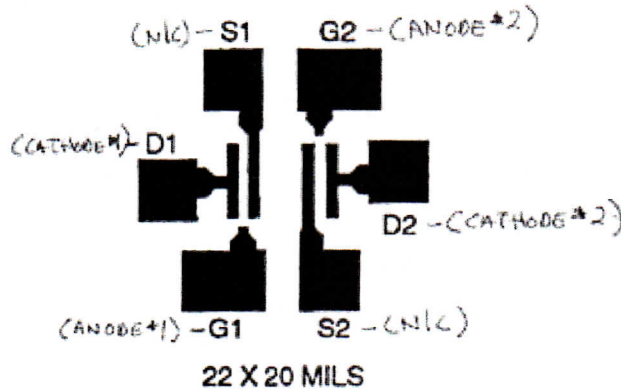




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Top Material: Aluminum
Backside Material: Gold
Bond Pad Size: .004" X .004" min.
Backside Potential: Drain
Mask Ref: 5007

APPROVED BY: DK

DIE SIZE .022x.020"

DATE: 6/3/16

MFG: Linear Systems

THICKNESS .010"

P/N: XPAD-5